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72 to support the heat radiator 70. The semiconductor assembly 10 is placed on the upper side of the heat radiator 70 supported by the support pin 42. After the semiconductor assembly 10 is disposed, the upper mold 34 is closed and the resin is injected into the cavity 38. After the resin is injected, the support pin 42 is pulled into the lower mold 36 at an appropriate time as shown by the solid line in Fig. 8, and the resin is cured as described.

IN THE CLAIMS:

Please cancel claims 10, 19, 23 and 28 without prejudice or disclaimer.

Please replace claims 1, 5, 11, 12, 15 and 24 as follows:

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1. (Amended) A method of manufacturing a semiconductor device comprising:
placing a semiconductor assembly in which a semiconductor chip is secured to a die pad of a lead frame in a cavity of a mold;
applying a pressure to the semiconductor assembly by at least one support pin so as to cause a stress in the lead frame;
sealing the semiconductor assembly with a resin injected into the cavity from a resin injection port of the mold; and
pulling the support pin from the cavity into the mold before the resin is cured to release the semiconductor assembly from the pressure applied by the support pin.

B3

5. (Twice Amended) The method of manufacturing a semiconductor device as defined in claim 1,

wherein the semiconductor assembly is pushed by the support pin in a direction away from the previous position of the contact portion of a support pin.

B4

11. (Amended) The method of manufacturing a semiconductor device as defined in claim 1,

wherein the support pin is caused to come in contact with a suspension lead that connects the die pad to a frame of the lead frame.